

RO4003C[™] and RO4350B[™] Laminates with TICER[™] TCR[®] Thin Film Resistor Foils

<u>RO4000</u>[°] Series High Frequency Circuit Materials are glass-reinforced hydrocarbon and ceramic (not PTFE) laminates designed for performance sensitive, high volume commercial applications.

<u>RO4000</u> laminates are designed to offer superior high frequency performance and low-cost circuit fabrication. The result is a low loss material which can be fabricated using standard epoxy/glass (FR-4) processes.

TICER[™] product brochures, resistor calculator and processing guidelines can be found at: http://www.ticertechnologies.com/technical-literature.

Data Sheet

Features:

- Glass-reinforced Hydrocarbon
 and ceramic dielectric
- Volume manufacturing process
- Excellent high-frequency performance
- Low Z-Axis expansion, excellent dimensional stability
- Integrated thin film resistor benefit
- CAF resistant

Typical Applications:

- Global communication system
- High reliability and complex
 multi-layer circuits
- Wireless communication devices

Property	Typical Value (3)		Direction	Units	Condition	Test Method (2)
	RO4003C	RO4350B				
Dielectric Constant, ϵ_r (Process specification)	3.38±0.05	3.48±0.05 ⁽¹⁾	Z	-	10 GHz/23°C	IPC-TM-650 2.5.5.5 Clamped Stripline
Dielectric Constant, ϵ_r (Design specification)	3.55	3.66	Z	-	FSR / 23°C	IPE-TM-650 2.5.5.6 FSR
Dissipation Factor tan, δ	0.0027 0.0021	0.0037 0.0031	Z	-	10GHz/23°C 2.5 GHz/23°C	IPC-TM-650, 2.5.5.5
Copper Peel Strength	0.88 (5)	0.70 (4)		N/mm (pli)	After Solder Float, ½ oz TCR foil	IPC-TM-650, 2.4.8
Flammability	N/A	V-0	-	-	-	UL 94

<u>RO4350B</u> 4 mil laminates have a process Dk of 3.33 ± 0.05 and are in conformance with IPC-4103A/240. All other <u>RO4350B</u> laminate thicknesses are /11 and /240 compliant.
 Clamped stripline method can potentially lower the actual dielectric constant due to the presence of air gap. Dielectric constant in practice may be higher than the values listed.

(3) Typical values are a representation of an average value for the population of the property. For specification values, contact Rogers Corporation.

Prolonged exposure in an oxidative environment may cause changes to the dielectric properties of hydrocarbon based materials. The rate of change increases at higher temperatures and is highly dependent on the circuit design. Although Rogers' high frequency materials have been used successfully in innumerable applications and reports of oxidation resulting in performance problems are extremely rare, Rogers recommends that the customer evaluate each material and design combination to determine fitness for use over the entire life of the end product.

Standard Thickness	Standard Panel Size
RO4003C: 0.008" (0.203mm), 0.012 (0.305mm), 0.016" (0.406mm), 0.020" (0.508mm) 0.032" (0.813mm), 0.060" (1.524mm) RO4350B: 0.0066" (0.168mm) 0.010" (0.254mm), 0.0133 (0.338mm), 0.0166 (0.422mm), 0.020" (0.508mm)0.030" (0.762mm), 0.060" (1.524mm)	12" X 18" (305 X457 mm) 24" X 18" (610 X 457 mm) Additional panel sizes may be available upon request.

The information contained in this document is intended to assist in you in designing with Rogers' circuit materials. It is not intended to and does not create any warranties, express or implied, including any warranty of merchantability or fitness for a particular purpose or that the results shown on this document will be achieved by a user for a particular purpose. The user is responsible for determining the suitability of Rogers' circuit materials for each application.

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